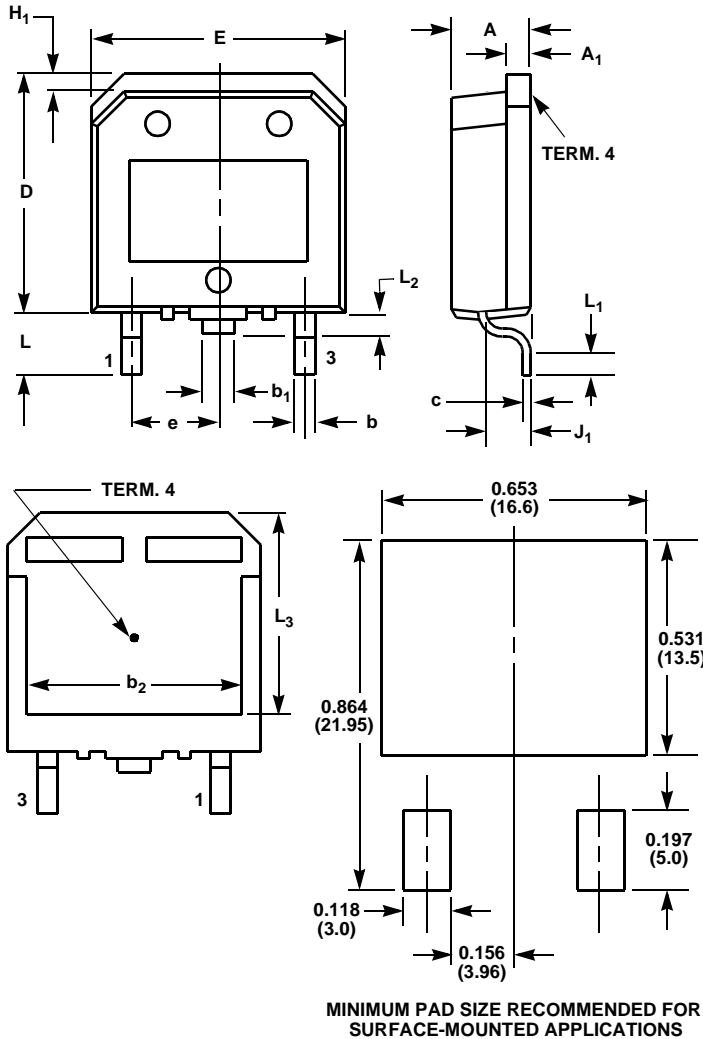


TO-268AA

SURFACE MOUNT JEDEC TO-268AA PLASTIC PACKAGE



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.19	0.200	4.90	5.10	-
A ₁	0.05	0.063	1.45	1.60	4, 5
b	0.04	0.057	1.15	1.45	4, 5
b ₁	0.07	0.082	1.90	2.10	4, 5
b ₂	0.52	0.535	13.3	13.6	2
c	0.01	0.025	0.40	0.65	4, 5
D	0.58	0.596	14.8	15.1	-
E	0.62	0.632	15.8	16.0	-
e	0.215 BSC		5.45 BS		7
H ₁	0.03	0.045	1.00	1.15	-
J ₁	0.10	0.114	2.70	2.90	-
L	0.15	0.155	3.90	3.95	4
L ₁	0.09	0.106	2.40	2.70	4, 6
L ₂	0.04	0.055	1.20	1.40	3
L ₃	0.48	0.500	12.4	12.7	2

NOTES:

1. These dimensions are within allowable dimensions of Rev. A. of JEDEC TO-268AA outline dated 6-95.
2. L₃ and b₂ dimensions establish a minimum mounting surface for terminal 4.
3. Solder finish uncontrolled in this area.
4. Dimension (without solder).
5. Add typically 0.002 inches (0.05mm) for solder plating.
6. L₁ is the terminal length for soldering.
7. Position of lead to be measured 0.120 inches (3.05mm) from bottom of dimension D.
8. Controlling dimension: Millimeter.
9. Revision 1 dated 2-99.